

Microsemi Corporation, a Microchip company

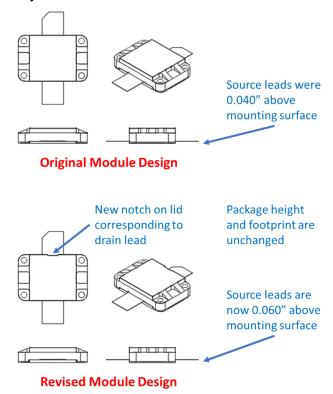
March 15, 2019

Product/Process Change Notification No: PSDS13021C0B44

Change Classification: Major

Subject: Material and manufacturing process change for VRF154FL and VRF157FL

Description of Change: Substrate thickness will change from 40 to 60 mil, the height of drain and gate leads will be 20 mil higher from the mounting surface, and the lead metal will change to Alloy 42.



Reason for Change: Improved reliability

Application Impact:

No electrical changes to the datasheets of these products are expected. Total height and footprint will not change.

Method of Identifying Changed Product:

Parts built with date code 1908 and later are with the new construction.

Products Affected by this Change:

VRF154FL, VRF157FL

Production Shipment Schedule:

For VRF157FL, there will be a transition period during which both constructions may be shipped. All VRF154FL parts will use the new construction starting immediately.

Qualification Data:

Qualification data will be made available.

Contact Information:

Microsemi, a Microchip company
Discrete and Power Management Group
Power Switching Discrete Solutions Business Unit
http://www.microsemi.com/salescontacts
Email: PCN Action@microsemi.com

Regards,

Microsemi, a Microchip company

Any projected dates in this PCN are based on the most current product information at the time this PCN is being issued, but they may change due to unforeseen circumstances. For the latest schedule and any other information, please contact your local Microsemi Sales Office, the factory contact shown above, or your local distributor.

This Product/Process Change Notification is confidential and proprietary information of Microsemi and is intended only for distribution by Microsemi to its customers, for customers' use only. It must not be copied or provided to any third party without Microsemi's prior written consent.





Microsemi Corporate Headquarters
One Enterprise, Aliso Viejo, CA 92656 USA
Within the USA: +1 (800) 713-4113
Outside the USA: +1 (949) 380-6100
Sales: +1 (949) 215-4996
E-mail: sales.support@microsemi.com

E-mail: <u>sales.support@microsemi.com</u> <u>www.microsemi.com</u>

©2016 Microsemi Corporation. All rights reserved. Microsemi and the Microsemi logo are registered trademarks of Microsemi Corporation. All other

Microsemi makes no warranty, representation, or guarantee regarding the information contained herein or the suitability of its products and services for any particular purpose, nor does Microsemi assume any liability whatsoever arising out of the application or use of any product or circuit. The products sold hereunder and any other products sold by Microsemi have been subject to limited testing and should not be used in conjunction with mission-critical equipment or applications. Any performance specifications are believed to be reliable but are not verified, and Buyer must conduct and complete all performance and other testing of the products, alone and together with, or installed in, any end-products. Buyer shall not rely on any data and performance specifications or parameters provided by Microsemi. It is the Buyer's responsibility to independently determine suitability of any products and to test and verify the same. The information provided by Microsemi hereunder is provided "as is, where is" and with all faults, and the entire risk associated with such information is entirely with the Buyer. Microsemi does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other IP rights, whether with regard to such information itself or anything described by such information. Information provided in this document is proprietary to Microsemi, and Microsemi reserves the right to make any changes to the information in this document or to any products and services at any time without provided.

About Microsemi

Microsemi Corporation (Nasdaq: MSCC) offers a comprehensive portfolio of semiconductor and system solutions for aerospace & defense, communications, data center and industrial markets. Products include high-performance and radiation-hardened analog mixed-signal integrated circuits, FPGAs, SoCs and ASICs; power management products; timing and synchronization devices and precise time solutions, setting the world's standard for time; voice processing devices; RF solutions; discrete components; enterprise storage and communication solutions; security technologies and scalable anti-tamper products; Ethernet solutions; Power-over-Ethernet ICs and midspans; as well as custom design capabilities and services. Microsemi is headquartered in Aliso Viejo, Calif., and has approximately 4,800 employees globally. Learn more at www.microsemi.com.